



Canfield Technologies, Inc.



FLOSAFE Lead-Free Solder

DESCRIPTION

FLOSAFE™ lead-free solder is alloyed from pure virgin metals.
Contains 97% Tin and 3% Copper.
Economical to use when lead-free solder is required.
Meets all State and Federal Specifications for potable water applications.

APPLICATIONS

Sealing, joining, coating and filling of all solderable metals. Used in plumbing, heating and industrial applications. The solder to use on brass, bronze, copper, galvanized iron, monel, steel, stainless steel and all other solderable alloys that require maximum reliability of solder joints.

FLUXES

For steel and copper use Canfield's **SOLDER-MATE®** Liquid Soldering Flux. For copper pipe use **COPPER-MATE®** Self-Cleaning Soldering Paste Flux or **AQUA-BRITE** Water Soluble Flux. On stainless steel use **SIL-CAN®** Liquid Soldering Flux.

TEMPERATURE RANGE:	440 - 590° F (room temperature)
SHEAR STRENGTH:	6,500 PSI (room temperature)
TENSILE STRENGTH:	5,500 PSI (room temperature)
DENSITY:	.264 pounds per cubic inch

PACKAGING

Packed 50 lbs. per carton on 1 lb. spools, .125 diameter. Other spool sizes and diameters upon request.

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